

PCN Number:	20190327002.0	PCN Date:	April 2, 2019
Title:	Datasheet for SN74LVC2G157		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



SN74LVC2G157

SCES207N – APRIL 1999 – REVISED MARCH 2019

Changes from Revision M (June 2015) to Revision N

Page

• Changed YZP package pinout drawing to match mechanical data drawing; and, pin functions description for clarity	3
• Added additional thermal metrics for all packages.....	5
• Added detailed feature description sections for Standard CMOS Inputs, Balanced High-Drive CMOS Push-Pull Outputs, and Negative Clamping Diodes.	8
• Added improved Design Requirements and Detailed Design Procedure.....	10
• Changed verbiage to better reflect recommendations for this specific device rather than logic devices in general.....	12
• Added layout example for the YZP package.....	12

The datasheet number will be changing.

Device Family	Change From:	Change To:
SN74LVC2G157	SCES207M	SCES207N

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/SN74LVC2G157>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

74LVC2G157DCTRE4	74LVC2G157DCURG4	74LVC2G157DCUTG4	SN74LVC2G157DCT3
SN74LVC2G157DCTR	SN74LVC2G157DCTRG4	SN74LVC2G157DCU3	SN74LVC2G157DCUR
SN74LVC2G157DCUT	SN74LVC2G157YZPR		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com